

	Title	Current OR
1	Method of making laminar stackable circuit board structure	29/852
2	Product for surface mount solder joints	428/601
3	Method of fabricating a multi-layer integrated circuit chip interposer	29/852
4	Method for replacing IC chip package interposer	29/830
5	Process for fabricating microwave and millimeter wave stripline filters	29/830
6	Process for preparing multi-layer printed wiring board	29/830
7	Metal transfer layers for parallel processing	29/830
8	Method of making rigid-flexible multilayer board system	29/830

	Current XRef
1	174/266; 257/E23.172; 428/901
2	174/261; 428/687
3	216/18; 216/20; 257/E23.067; 257/E23.171; 29/830
4	257/E23.067; 257/E23.171; 29/402.06; 29/402.08; 29/831
5	156/89.12; 156/89.14; 156/89.15; 156/89.17; 156/89.18; 333/204; 333/238; 430/314
6	216/20; 216/67
7	174/262; 216/17; 216/33; 257/E23.173; 29/846; 428/901
8	228/180.1; 228/180.21; 29/840; 439/44; 439/47; 439/48; 439/67

	Title	Current OR
9	Method of manufacturing multilayered printed-wiring-board	29/830
10	Multilayer circuit board fabricated from silicon	333/238

	Current XRef
9	174/259; 228/111.5; 228/175; 29/840; 361/776; 361/804
10	228/180.22; 29/830; 361/792; 428/450; 428/901